



6715/64322

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application;

1. (Previously Presented) An electronics packaging system comprising:

a printer to print solder on lands of a printed wiring board;

a placing unit to place electronic parts on the lands of the printed wiring board having the solder printed thereon by the printer; and

a reflow unit to heat the printed wiring board on which the electronic parts have been placed by the placing unit and to solder the electronic parts to the printed wiring board,

the printed wiring board being brought by a transfer mechanism, while being held in generally upright position, in order through the printer, the placing unit and the reflow unit.

2. (Previously Presented) The system according to claim 1, wherein:

land-position information is generated by a detecting mechanism provided in the printer before the solder is printed by the printer on the lands of the printed wiring board; and

the placing unit places the electronic parts on the printed wiring board based on the land-position information.

3. - 17. (Cancelled)